

CH03-CJ - SIM CARD HOLDER, CONTACT TYPE, WITHOUT SWITCH, 8 PINS

FEATURES

- 1. GENERAL CHARACTERISTICS
 - DIMENSIONS: 23.62L x 10.16W x 1.3H mm
 - WEIGHT: APPROX. 0.5±0.1g
 - CONTACT PRINCIPLE: FRICTION TECHNOLOGY
 - MOUNTING SYSTEM: SMT TYPE OPTIONAL POST
 - DURABILITY: 100,000 CYCLES MIN.

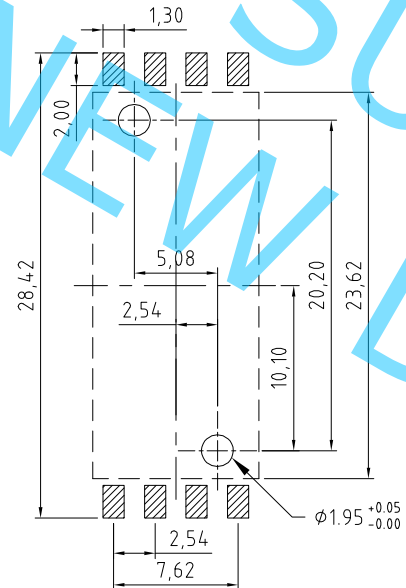
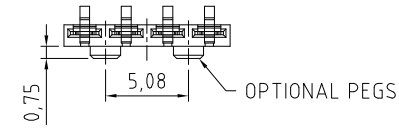
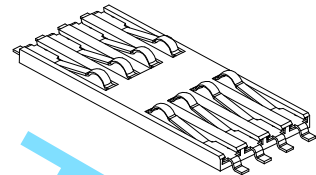
- 2. MECHANICAL CHARACTERISTICS
 - INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0
 - CONTACT MATERIAL: PHOSPHOR BRONZE
 - CONTACT AREA PLATING: GOLD FLASH OVER NICKEL

- 3. ELECTRICAL CHARACTERISTICS
 - CONTACT RESISTANCE: 50m OHMS TYP. 100m OHMS MAX.
 - INSULATION RESISTANCE: >1000M OHMS / 500V DC
 - RATED CURRENT: 1A MAX, 10uA MIN.
 - RATED VOLTAGE: 50V MAX.
 - WITHSTANDING DIELECTRIC VOLTAGE: 500V AC R.M.S. FOR 1 MINUTE

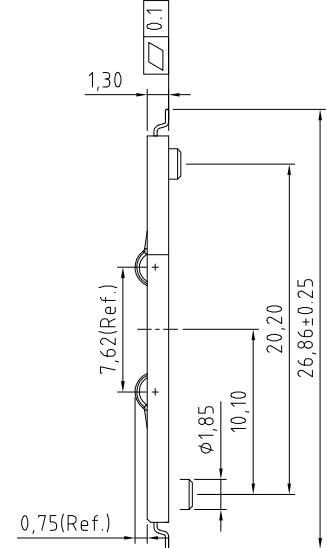
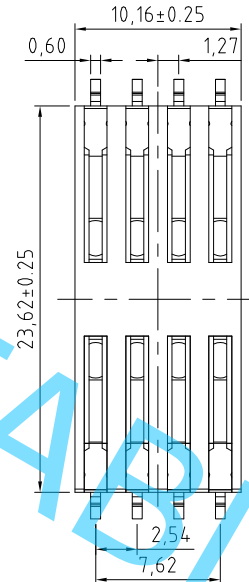
- 4. SOLDERABILITY
 - WAVE: NOT APPLICABLE
 - IR REFLOW: 250°C, 5 SEC. MAX.
 - MANUAL SOLDERING: 360°C, 3 SEC. MAX.

- 5. ENVIRONMENTAL CHARACTERISTICS
 - OPERATING TEMPERATURE: -40°C ~ +85°C
 - OPERATING HUMIDITY: 10% ~ 95% RH
 - STORAGE TEMPERATURE: -40°C ~ +85°C
 - STORAGE HUMIDITY: 10% ~ 95% RH
 - THERMAL SHOCK: -40°C ~ +85°C, 5 CYCLES
 - DAMP HEAT: 40°C, 90% RH, 240HR
 - SALT-MIST: 35°C, 5% NaCl, 24HR

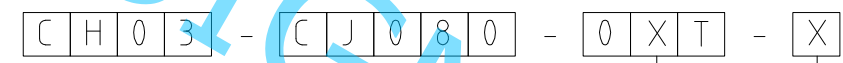
- NOTES:
- 1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.
 - 2. PACKAGING: 1,000PCS/REEL.



COMPONENT SIDE (TOLERANCE: ±0.05)
RECOMMENDED PCB LAYOUT



HOW TO ORDER



LOCATING PEG OPTIONS:
A = WITH PEGS
B = WITHOUT PEG

'H' HEIGHT OPTIONS:
A = 1.30MM

10	26/10/11 - NYW RELEASE
11	28/11/14 - NYW
12	09/08/17 - NYW REMOVE PROFILE OPTION B
13	19/02/19 - NYW REMOVE PACKAGING TO TAPE & REEL

Scale:	3:1	THIRD ANGLE	Unstated Tolerances: X ±0.35 .X ±0.25 .XX ±0.15 XXX ±0.10	Material	SEE NOTE
Drawn:	NYW				
App'd:	XXXX	Title	SIM CARD ACCEPTOR	NOT TO SCALE	
Date:	18 FEB. '19	Revision:	1.3	Unit:	mm

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Type:	CH03-CJ
Drawing Number:	CH03-CJ
Sheet	1 of 1
Drawing	© E and O E